



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

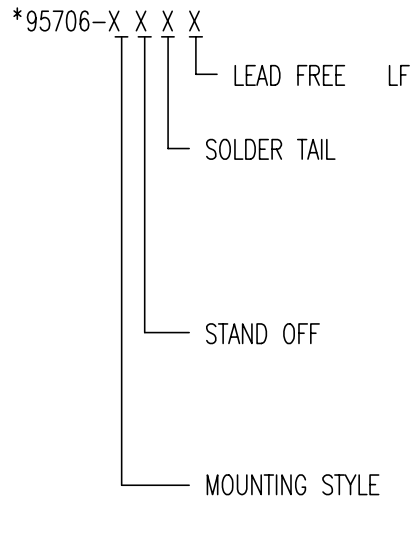
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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



PRODUCT NO. *95706-XXX	STAND OFF DIM "M" (mm)	SOLDER TAIL	DIM "P" (mm)	SHEET NO.	MOUNTING STYLE TO PCB
000	0	R/A	2.8	NO.2	TOP MOUNT 95706-0XX BLACK COLOR
000LF	0	R/A	2.8		
001	0	SMT STAGGERED	--/--		
002	0	SMT IN LINE	--/--		
010	4	R/A	2.8	NO.3	
020	5	R/A	2.8		
040	2	R/A	2.5		
010LF	4	R/A	2.8		
020LF	5	R/A	2.8		
040LF	2	R/A	2.5		
500	0	R/A	2.8	NO.4	BOTTOM MOUNT 95706-5XX
500LF	0	R/A	2.8		
501	0	SMT STAGGERED	--/--		
502	0	SMT IN LINE	--/--		
510	4	R/A	2.8	NO.5	
520	5	R/A	2.8		
540	2	R/A	2.5		
510LF	4	R/A	2.8		
520LF	5	R/A	2.8		
540LF	2	R/A	2.5		

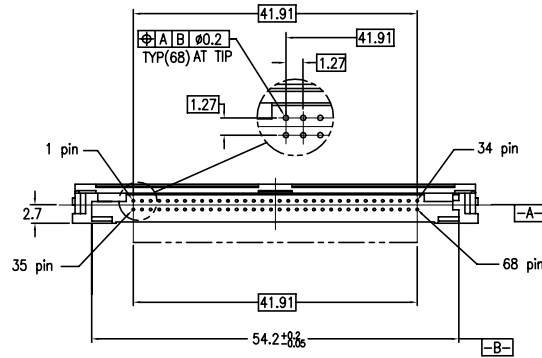
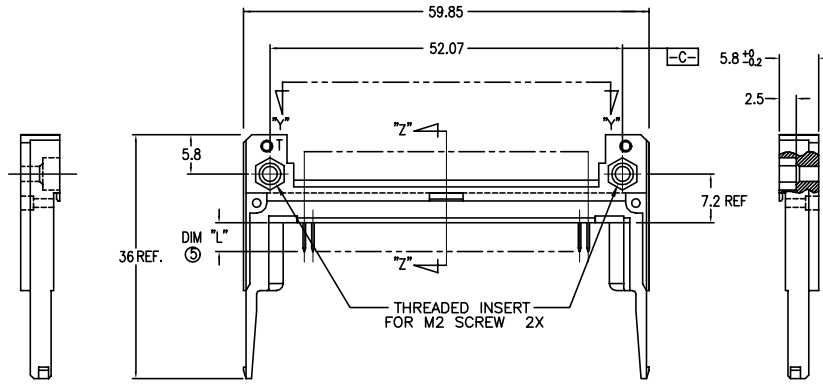


- 0 : R/A (FOR LOWER & SINGLE)
- 1 : SMT STAGGERED (FOR LOWER ONLY)
- 2 : SMT IN LINE (FOR LOWER ONLY)
- 5 : R/A (FOR UPPER ONLY)
- 0 : 0mm
- 1 : 4mm
- 2 : 5mm
- 4 : 2mm
- 0 : TOP MOUNTING
- 5 : BOTTOM MOUNTING

mat'l. code		surface / tolerance		projection		product family	
		ISO1302 / ISO1101 ISO406				MCS	
ltr ecn nodr		date		tolerances unless otherwise specified		title	
B V00619 RGD		3/30/00		0.X±0.3		68 POS. EJECTOR HEADER ASSY.	
C N05-0048 WB		05/29/03		0.XX±0.13		FOR LOW VOLTAGE	
D BX-N-011445 ZK		04/02/12		0.XXX±0.051		scale 1:1	
		dr S.DUESTERHOEFT		7/20/95		dwg no sheet 1 of 5 size	
		enr D.BRANN		7/20/95		95706 A4	
		chr D.BRANN		7/20/95		type Product Customer Drawing	
		appd D.BRANN		7/20/95			
sheet index	revision	D	D	D	D	D	
	sheet	1	2	3	4	5	



PRODUCT NO.
95706-000/000LF
95706-001
95706-002



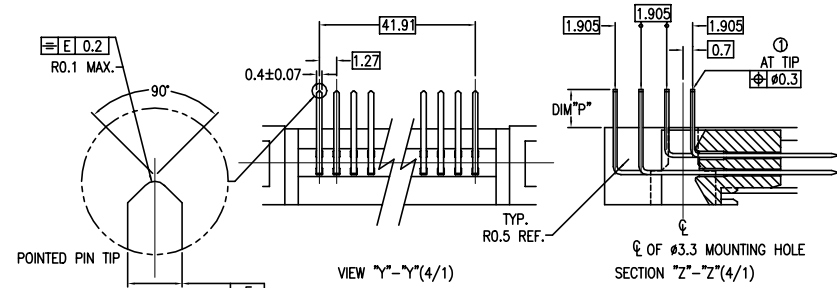
NOTES

- ① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF
- ② SEE TA-946 FOR PCB LAYOUT
- ③ MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : PHOSPHOR BRONZE
- ④ FINISH
PIN
UNDER PLATING : 0.5µm MIN. Ni
CONTACT AREA : 0.076 µm MIN. GOLD

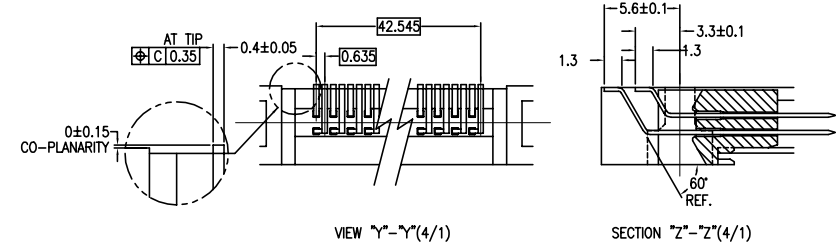
SOLDER AREA(TIN LEAD OPTION): 2.5µm MIN. Sn-Pb
SOLDER AREA(LEAD FREE OPTION): 2.5µm MIN. PURE TIN
- ⑤ SEQUENCE PIN ASSIGNMENT

PIN No.	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36.67	1.1734	35.5188

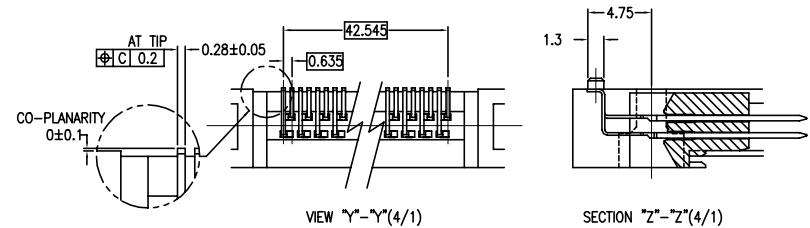
- 6 GENERAL TOLERANCE : ±0.3
- 7 IF LEAD FREE P/N. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE
SOLDER TAIL : SMT-IL, SMT-STG CAN RESIST 40 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
SOLDER TAIL : R/A CAN RESIST 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- 8 IF LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- 9 PRODUCT SPEC:110-263



R/A (95706-000/000LF)



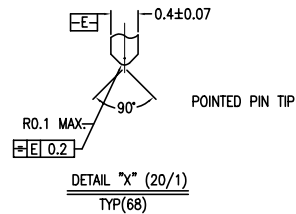
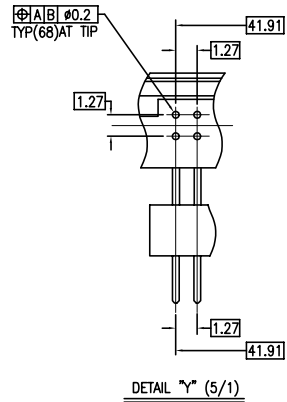
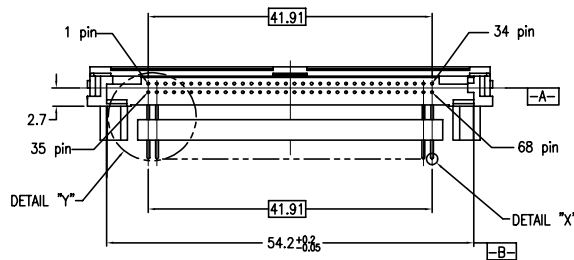
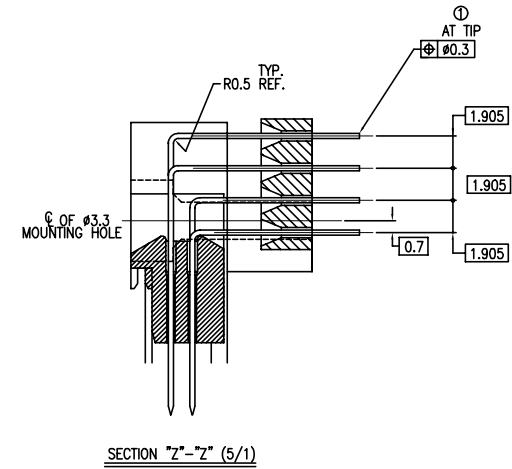
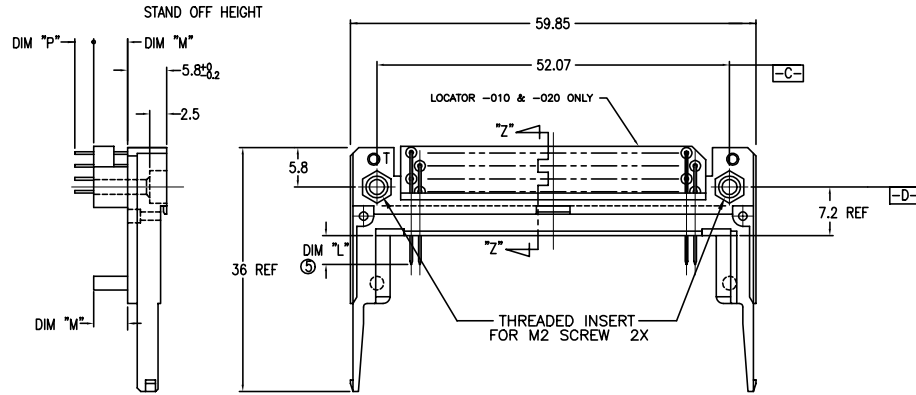
SMT STAGGERED (95706-001)



SMT IN LINE (95706-002)

mat'l. code	surface ISO1302 ✓	tolerance ISO1101 ISO406	projection MM	product family MCS
ltr ecn nodr date	tolerances unless other wise specified		MM	68 POS. EJECTOR HEADER ASSY. FOR LOW VOLTAGE
D	angle 0°±2'	0.X±0.3 0.XX±0.13 0.XXX±0.051	scale 1:1	dwg no 95706 sheet 2 of 5 size A4
	dr S.DUESTERHOEFT	7/20/95		
	enr D.BRANN	7/20/95		
	chr D.BRANN	7/20/95		
	appd D.BRANN	7/20/95		
sheet index	revision sheet			type Product Customer Drawing

PRODUCT NO.
95706-010/010LF
95706-020/020LF
95706-040/040LF



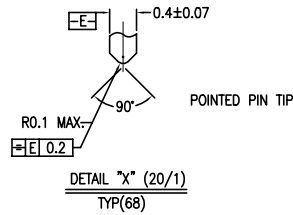
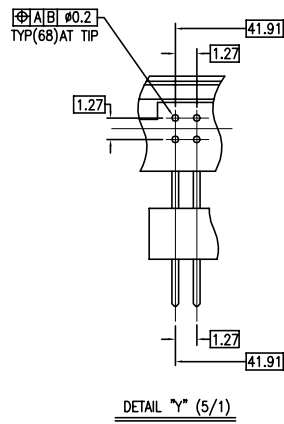
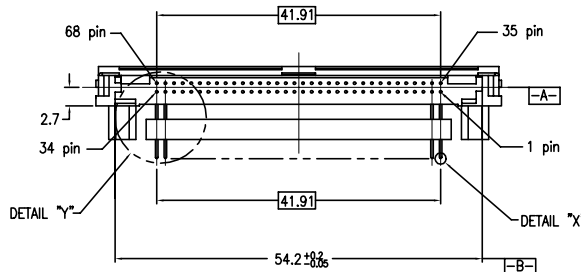
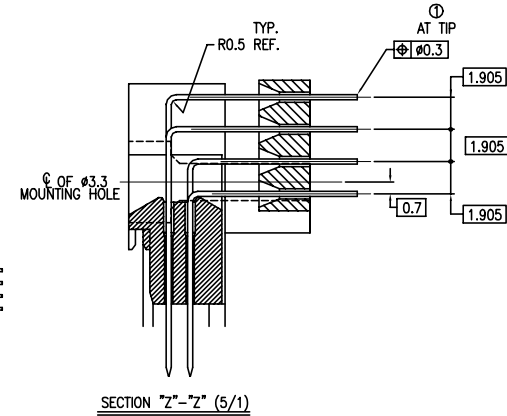
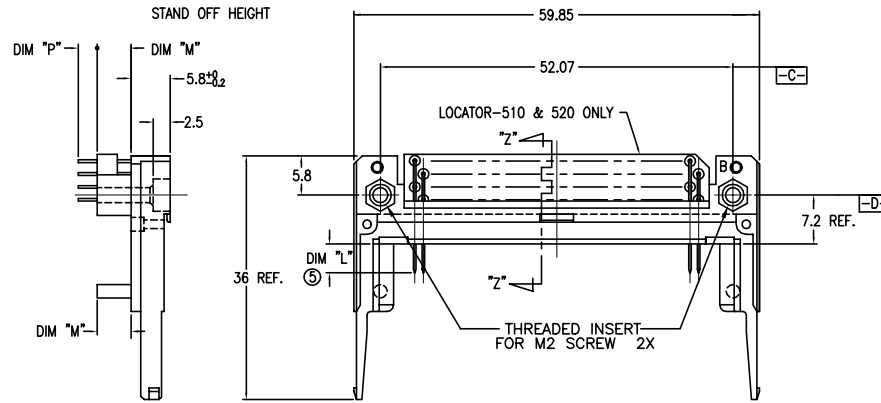
NOTES

- TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
 - SEE TA-946 FOR PCB LAYOUT.
 - MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : PHOSPHOR BRONZE.
 - FINISH
PIN
UNDER PLATING : 0.5 μ m MIN. Ni.
CONTACT AREA : 0.076 μ m MIN. GOLD

SOLDER AREA(TIN LEAD OPTION): 2.5 μ m MIN. Sn-Pb
SOLDER AREA(LEAD FREE OPTION): 2.5 μ m MIN. PURE TIN
 - SEQUENCE PIN ASSIGNMENT
- | PIN No. | DIM "L" | | |
|---------|----------------|---------------|---------------|
| | 4.25 \pm 0.1 | 3.5 \pm 0.1 | 5.0 \pm 0.1 |
| OTHERS | 36.67 | 17.54 | 35.51.68 |
- GENERAL TOLERANCE : \pm 0.3
 - IF LEAD FREE P/N. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE
SOLDER TAIL : SMT-IL, SMT-STG CAN RESIST 40 SECONDS IN A CONVECTION, INFRARED OR VAPOR PHASE REFLOW OVEN.
SOLDER TAIL : R/A CAN RESIST 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
 - IF LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
 - PRODUCT SPEC:110-263

mat'l. code	surface ISO1302	tolerance ISO1101 ISO406	projection ⊕	product family MCS
l trechn nodr date	tolerances unless otherwise specified		MM	68 POS. EJECTOR HEADER ASSY. FOR LOW VOLTAGE
D	angle ⊕	0.X \pm 0.3	scale 1:1	dwg no 95706 sheet 3 of 5 size A4
	0 \pm 2'	0.XX \pm 0.051		type Product Customer Drawing
	dr S.DUESTERHOEFT	7/20/95		
	engr D.BRANN	7/20/95		
	chr D.BRANN	7/20/95		
	appd D.BRANN	7/20/95		
sheet index	revision sheet			

PRODUCT NO.
95706-510/510LF
95706-520/520LF
95706-540/540LF



NOTES

- TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF
- SEE TA-946 FOR PCB LAYOUT
- MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 NATURAL
PIN : PHOSPHOR BRONZE
- FINISH PIN
UNDER PLATING : 0.5µm MIN. Ni
CONTACT AREA : 0.076 µm MIN. GOLD

SOLDER AREA(TIN LEAD OPTION): 2.5µm MIN. Sn-Pb
SOLDER AREA(LEAD FREE OPTION): 2.5µm MIN. PURE TIN
- SEQUENCE PIN ASSIGNMENT

	DIM "M"
4.25±0.1	3.5±0.1
36.67	1.77±0.14
	3.5±0.68
- GENERAL TOLERANCE : ±0.3
- IF LEAD FREE P/N. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE
SOLDER TAIL : SMT-IL, SMT-STG CAN RESIST 40 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
SOLDER TAIL : R/A CAN RESIST 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC:110-263

mat'l. code	surface ISO1302 ✓	tolerance ISO1101 ISO406	projection MM	product family MCS
l trechn nodr date	tolerances unless otherwise specified		scale 1:1	title 68 POS. EJECTOR HEADER ASSY. FOR LOW VOLTAGE
D	angle 0°±2'	0.X±0.3 0.XX±0.13 0.XXX±0.051	MM	dwg no 95706
	dr S.DUESTERHOEF	7/20/95	FCI	sheet 5 of 5 size A4
	enr D.BRANN	7/20/95		type Product Customer Drawing
	chr D.BRANN	7/20/95		
	appd D.BRANN	7/20/95		
sheet index	revision sheet			